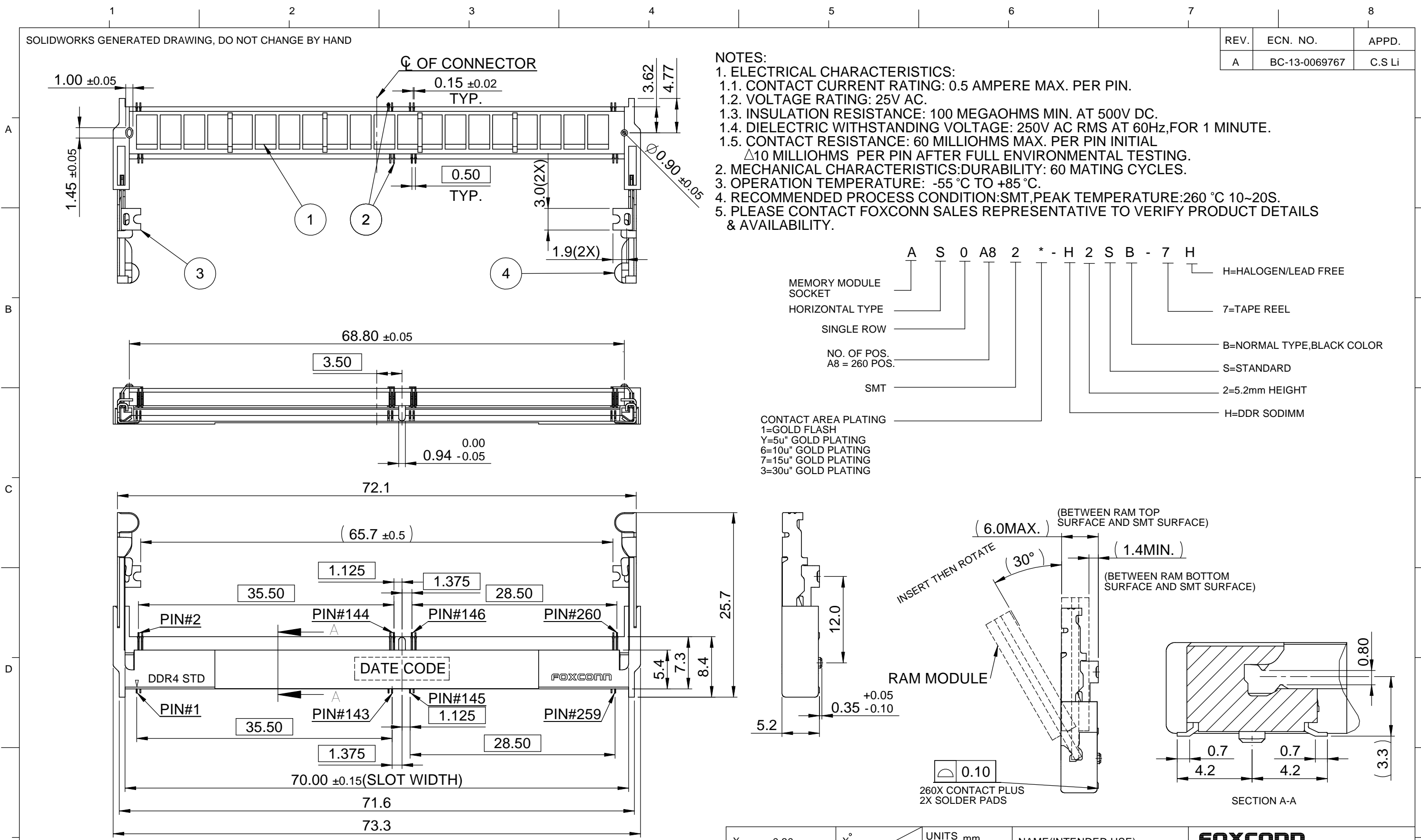


SOLIDWORKS GENERATED DRAWING, DO NOT CHANGE BY HAND

REV.	ECN. NO.	APPD.
A	BC-13-0069767	C.S Li

**NOTES:**

- ELECTRICAL CHARACTERISTICS:
  - CONTACT CURRENT RATING: 0.5 AMPERE MAX. PER PIN.
  - VOLTAGE RATING: 25V AC.
  - INSULATION RESISTANCE: 100 MEGAOHMS MIN. AT 500V DC.
  - DIELECTRIC WITHSTANDING VOLTAGE: 250V AC RMS AT 60Hz, FOR 1 MINUTE.
  - CONTACT RESISTANCE: 60 MILLIOHMS MAX. PER PIN INITIAL  
 $\Delta$ 10 MILLIOHMS PER PIN AFTER FULL ENVIRONMENTAL TESTING.
- MECHANICAL CHARACTERISTICS: DURABILITY: 60 MATING CYCLES.
- OPERATION TEMPERATURE: -55 °C TO +85 °C.
- RECOMMENDED PROCESS CONDITION: SMT, PEAK TEMPERATURE: 260 °C 10-20S.
- PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY.



MEMORY MODULE SOCKET  
 HORIZONTAL TYPE  
 SINGLE ROW  
 NO. OF POS. A8 = 260 POS.  
 SMT

AS0A82\*-H2SB-7H

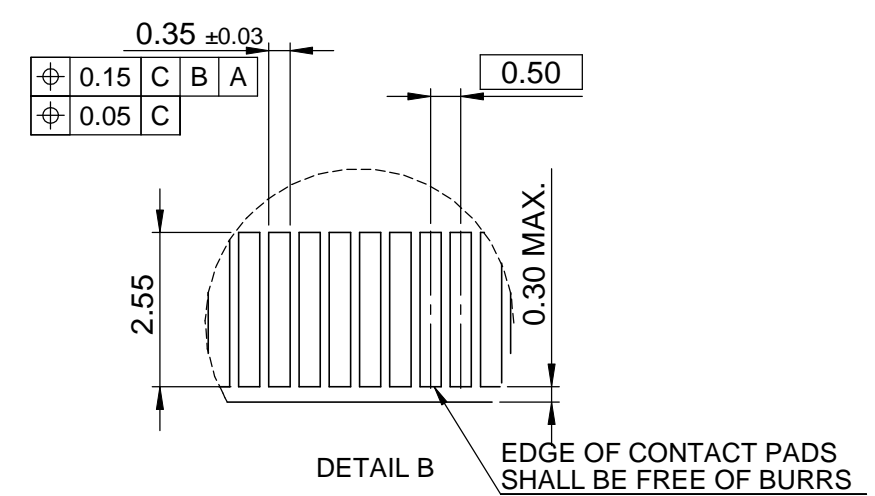
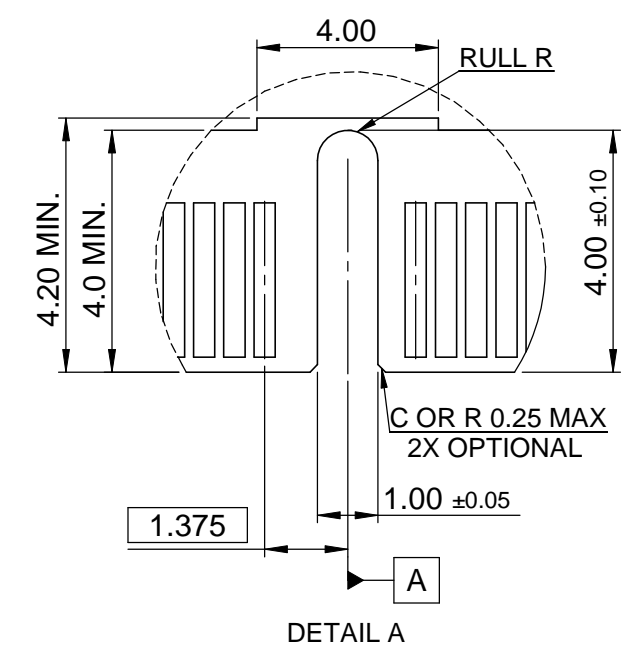
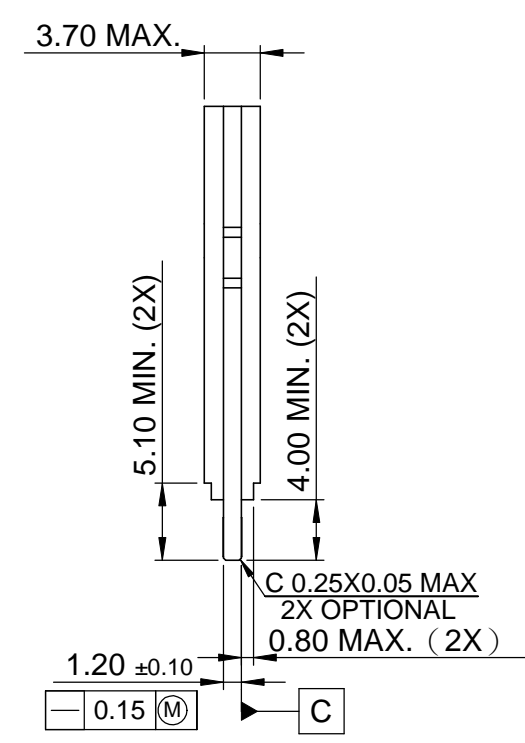
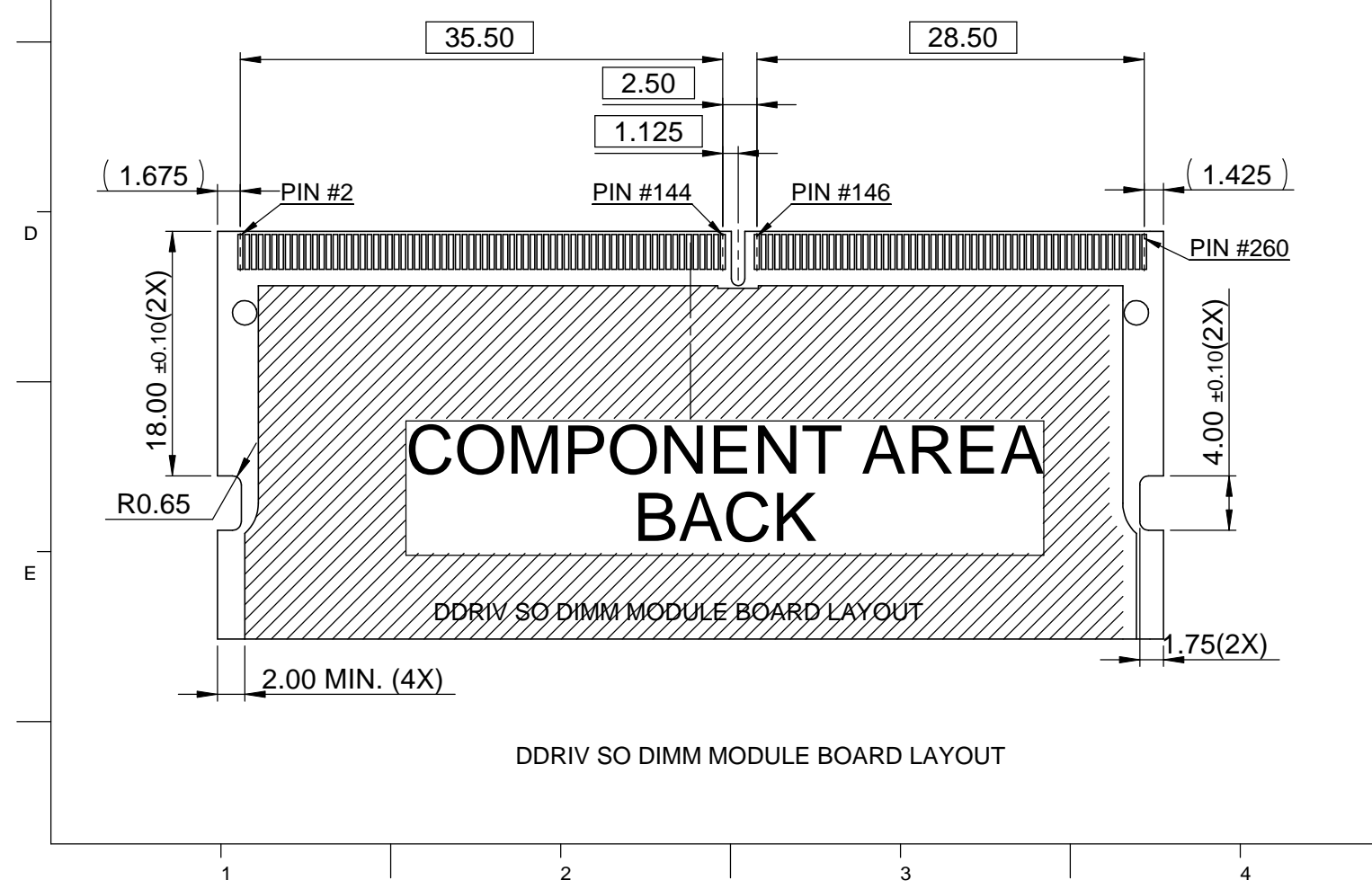
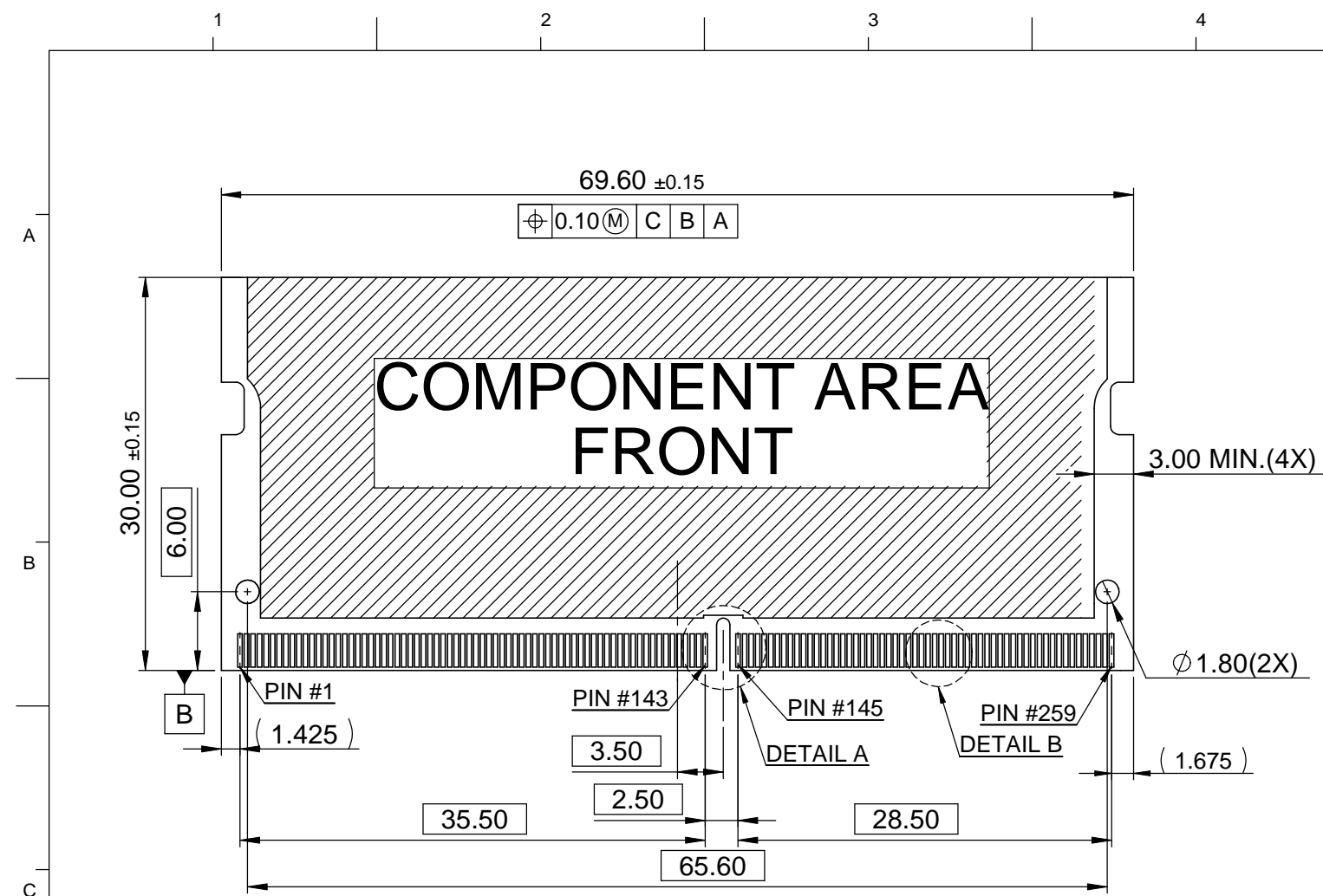
H=HALOGEN/LEAD FREE  
 7=TAPE REEL  
 B=NORMAL TYPE, BLACK COLOR  
 S=STANDARD  
 2=5.2mm HEIGHT  
 H=DDR SODIMM

CONTACT AREA PLATING  
 1=GOLD FLASH  
 Y=5u" GOLD PLATING  
 6=10u" GOLD PLATING  
 7=15u" GOLD PLATING  
 3=30u" GOLD PLATING

ITEM	DESCRIPTION	Q'TY	MATERIAL	TREATMENT
4	METAL SPRING	2	STAINLESS STEEL	ULTRASONIC CLEANING
3	METAL PAD	2	STAINLESS STEEL	10u" NICKEL UNDER PLATING 100u" MATTE TIN PLATING OVER SOLDER PAD AREA
2	CONTACT	260	COPPER ALLOY	50u" NICKEL UNDER PLATING GOLD FLASH OR 5u" OR 10u" OR 15u" OR 30u" GOLD PLATING AT CONTACT AREA; GOLD FLASH PLATING AT TAIL
1	HOUSING	1	THERMOPLASTIC	UL94V-0, HALOGEN FREE, BLACK COLOR

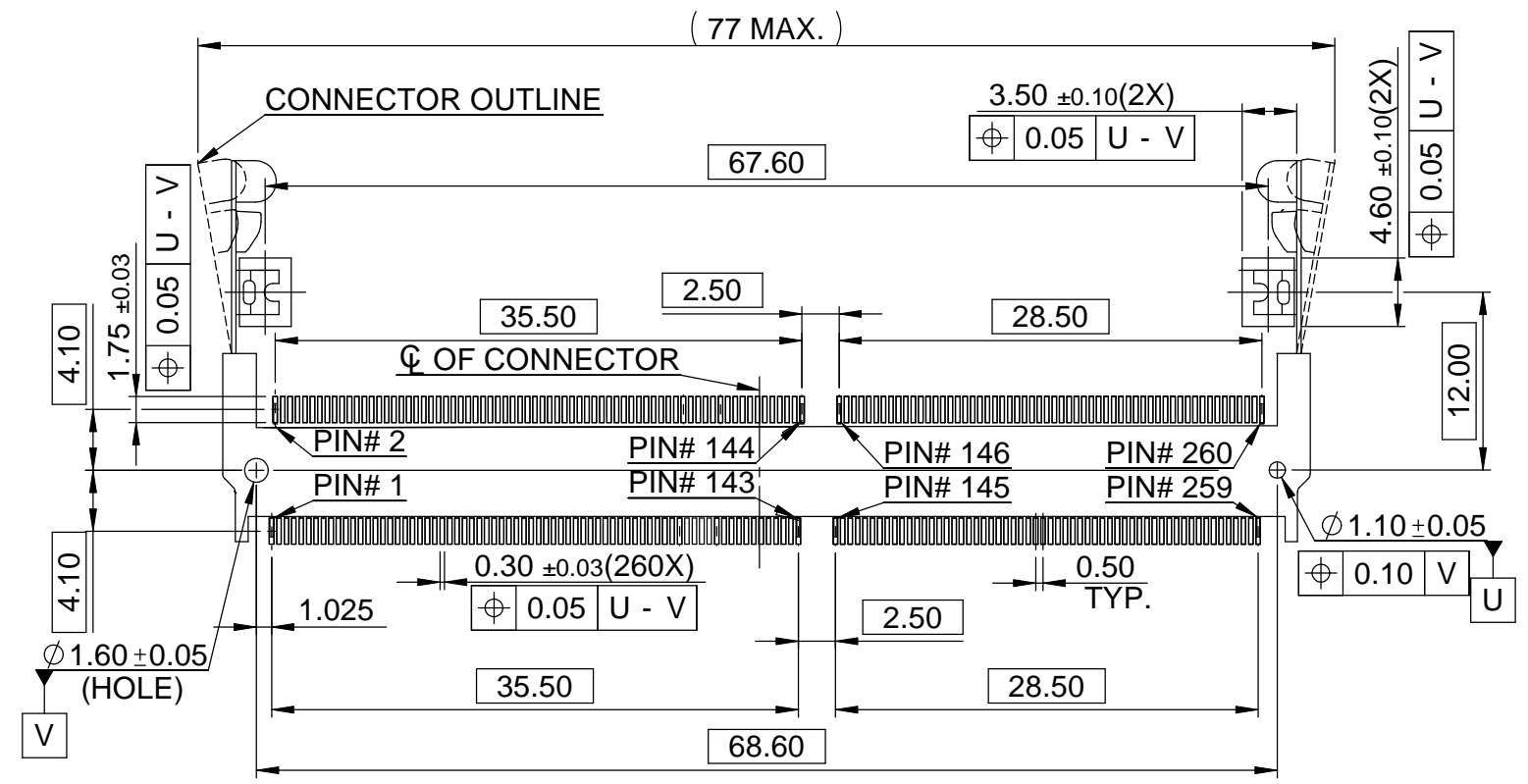
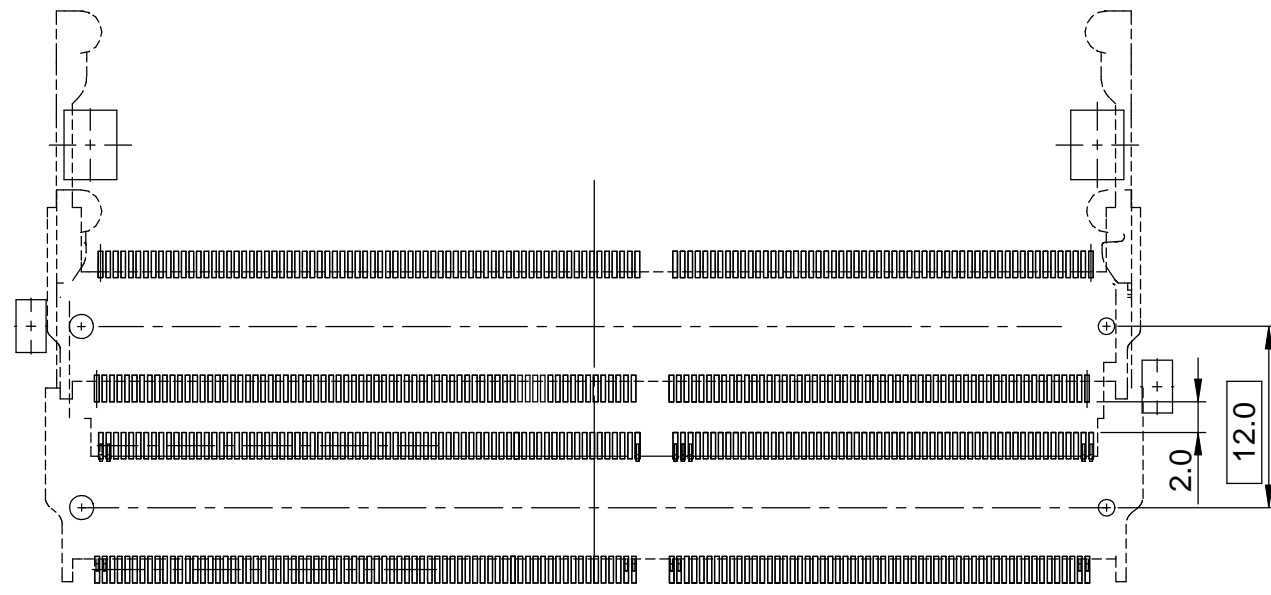
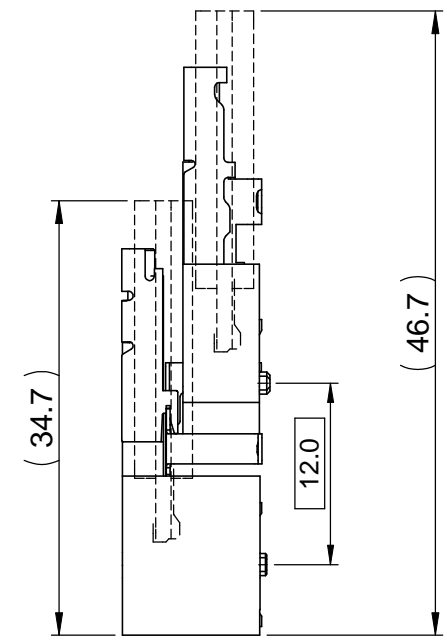
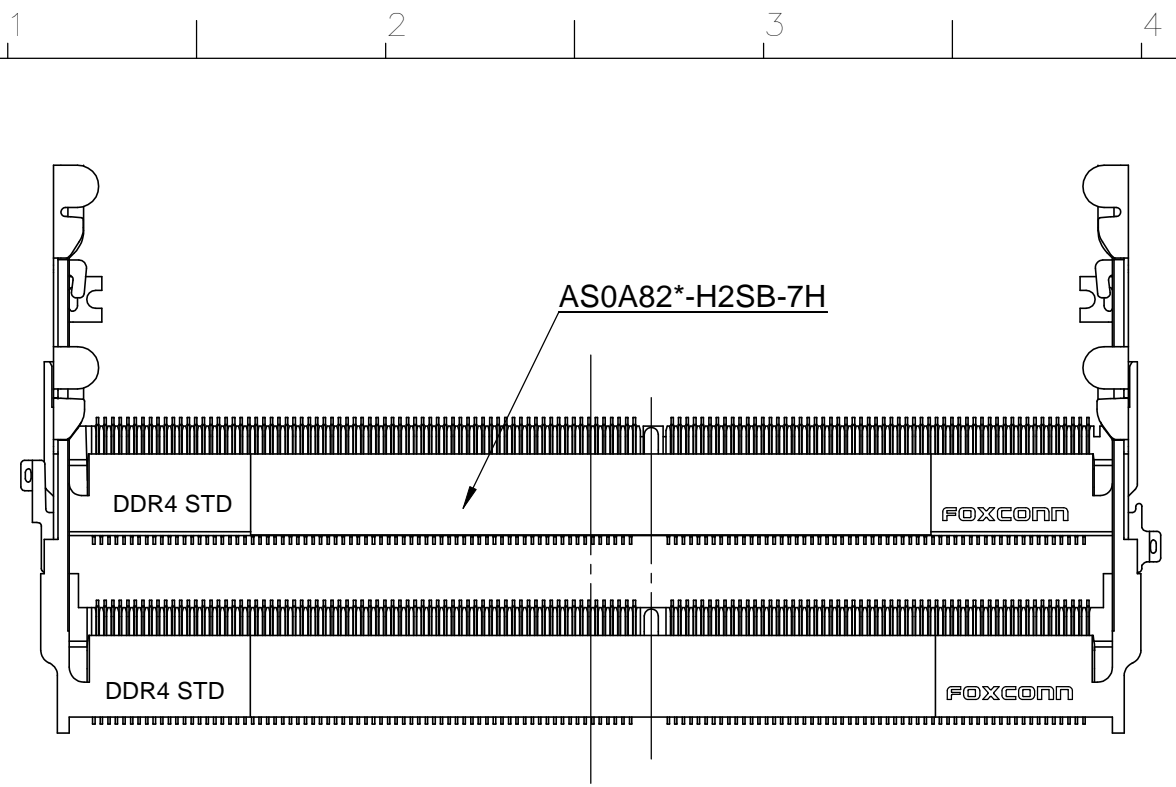
X. ± 0.30	X° ±	UNITS mm	NAME (INTENDED USE)	<b>FOXCONN</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ± 0.25	.X° ±		DDR4 SO DIMM CONN.	
.XX ± 0.15	.XX° ±	MAT'L	PART NO. (INTENDED USE)	TITLE:
.XXX ±	.XXX° ±		AS0A82*-H2SB-7H	CUSTOMER DRAWING 260PIN SODDR4 5.2 STD.
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			CHKD: Alex Wang	317-0000-2252
Q'TY			DR: Gary Xu 2013/10/11	SCALE SHEET REV.
				N/A 1/5 A

REV.	ECN. NO.	APPD.



X. ± 0.25	X. °	UNITS mm	NAME (INTENDED USE)	<b>FOXCONN</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ± 0.10	.X °		DDR4 SO DIMM CONN.	
.XX ± 0.05	.XX °	MAT'L	PART NO. (INTENDED USE)	TITLE:
.XXX ±	.XXX °		AS0A82*-H2SB-7H	CUSTOMER DRAWING 260PIN SODDR4 5.2 STD.
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED. AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			FINISH	DWG NO.:
			QTY	317-0000-2252
APPD: C.S Li			CHKD: Alex Wang	
DR: Gary Xu 2013/10/11			DR: Gary Xu 2013/10/11	
			SCALE	SHEET
			N/A	2/5
			REV.	A

REV.	ECN. NO.	APPD.

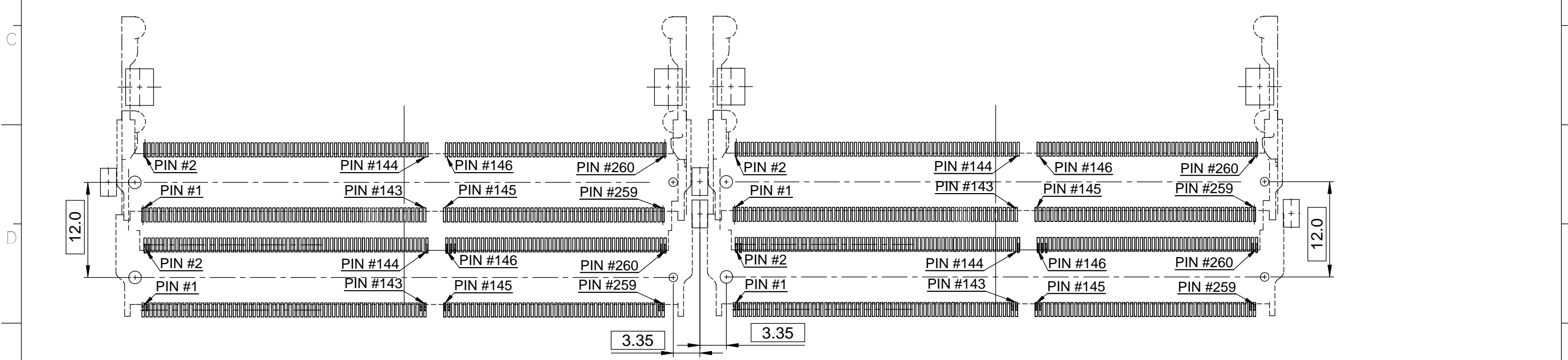
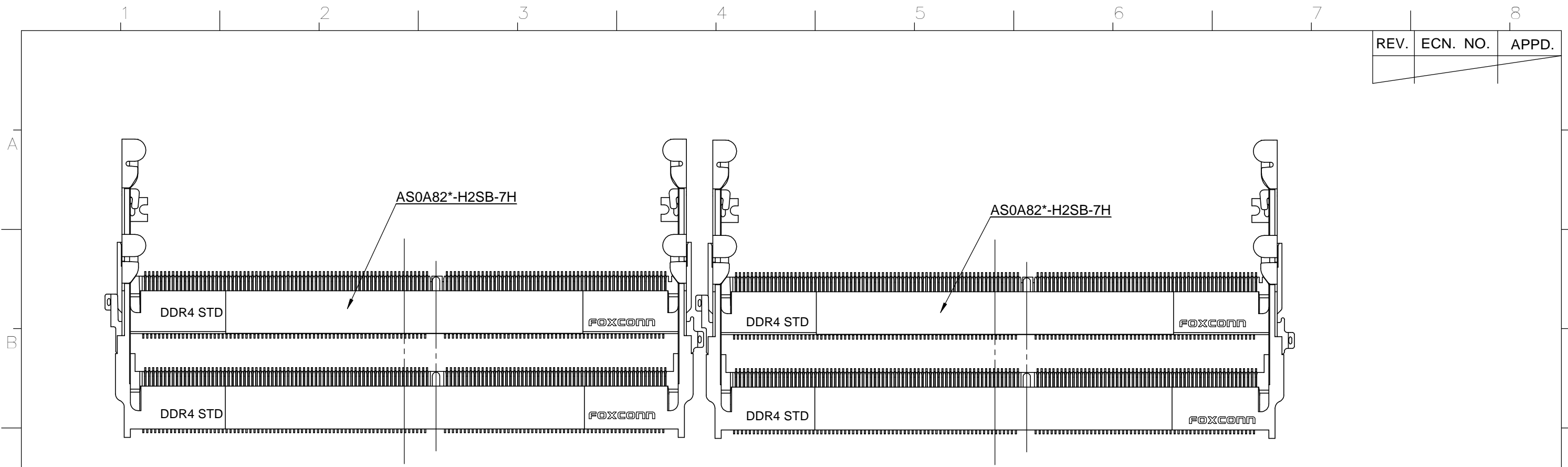


P.C.B. LAYOUT(STACKED ORIENTATION)

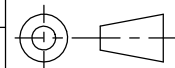
P.C.B. LAYOUT(RECOMMEND THICKNESS = 1.40MM)

X. ± 0.25	X° ±	UNITS mm	NAME (INTENDED USE) DDR4 SODIMM CONN	<b>FOXCONN</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.				
.X ± 0.15	.X° ±				PART NO. (INTENDED USE) AS0A82*-H2SB-7H	TITLE: CUSTOMER DRAWING 260PIN SODDDR4 5.2 STD.		
.XX ± 0.05	.XX° ±						APPD: C.S Li	DWG NO.: 317-0000-2252
.XXX ±	.XXX° ±							
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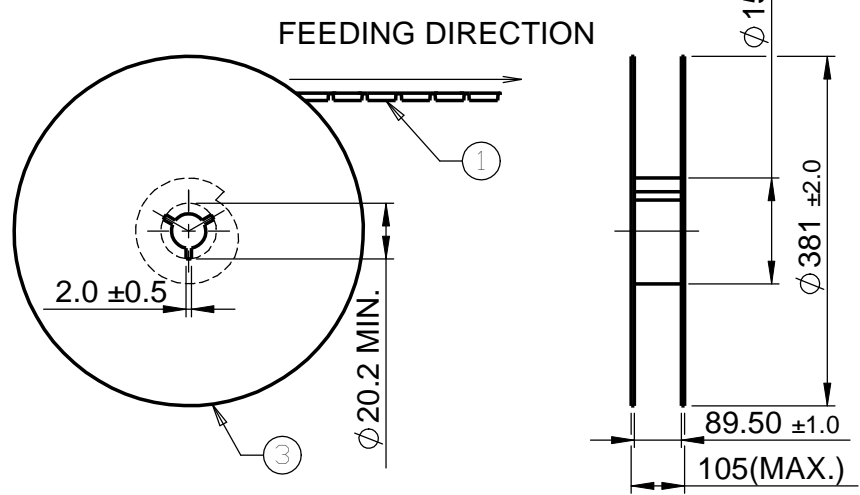
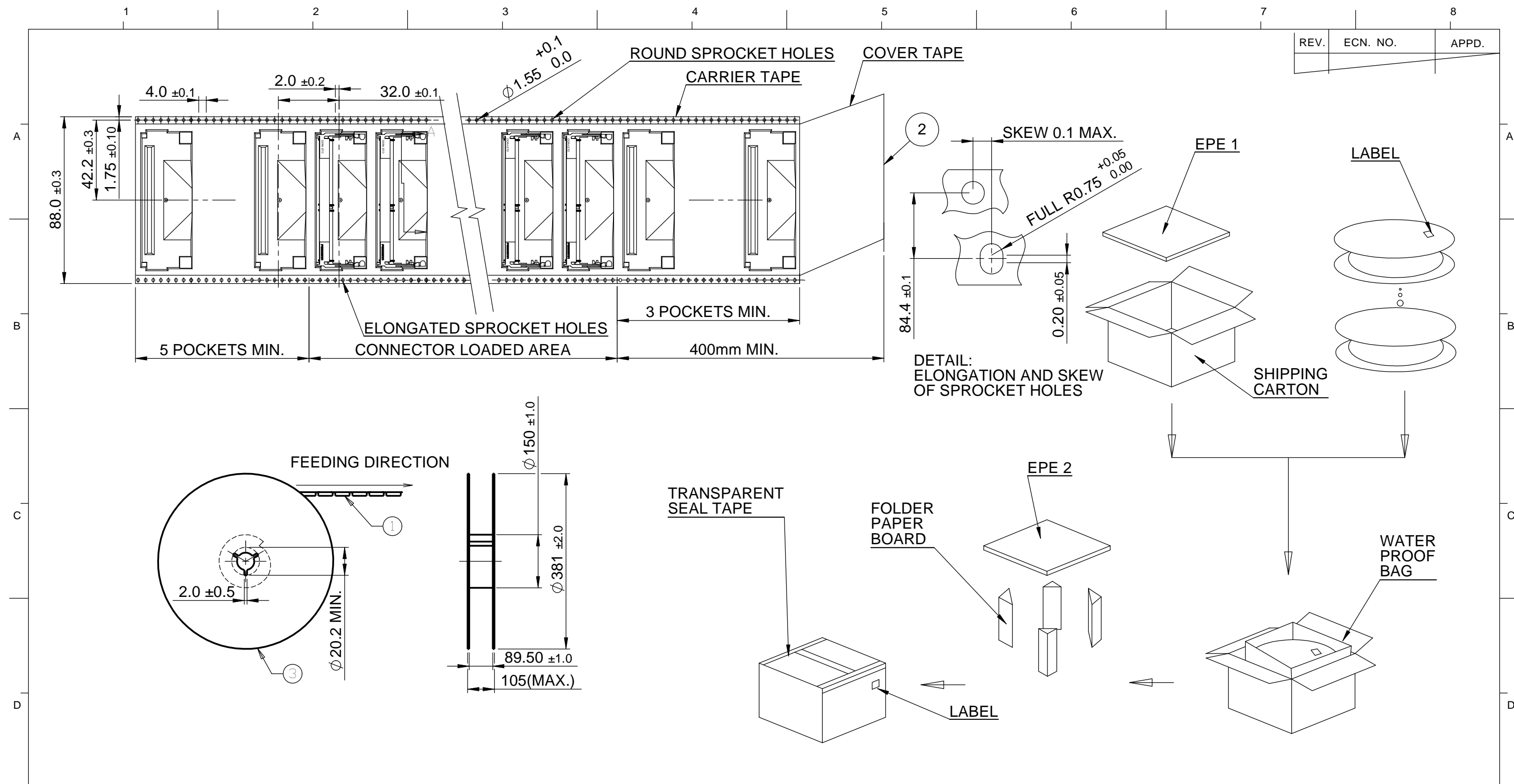
REV.	ECN. NO.	APPD.



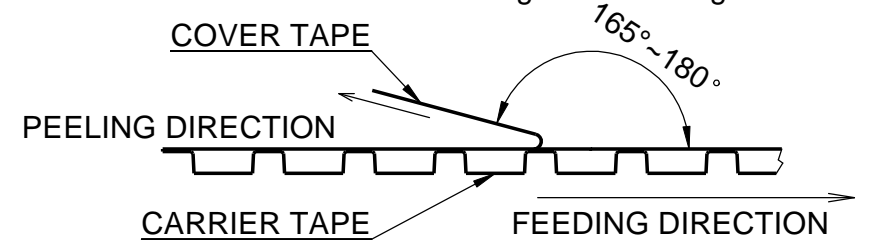
P.C.B. LAYOUT(DUAL COMPRESSED STACKED ORIENTATION)

X. ± 0.25	X° ±	UNITS mm	NAME(INTENDED USE) DDR4 SODIMM CONN	<b>FOXCONN</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.						
.X ± 0.10	.X° ±				MAT'L					
.XX ± 0.05	.XX° ±	FINISH	PART NO.(INTENDED USE) <b>AS0A82*-H2SB-7H</b>	TITLE: CUSTOMER DRAWING 260PIN SODDDR4 5.2 STD.						
.XXX ±	.XXX° ±		APPD: C.S Li	DWG NO.: 317-0000-2252						
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			SCALE		SHEET	REV.				
N/A	4/5	A								
			DR: Gary Xu 10/08'13							

REV.	ECN. NO.	APPD.



- NOTES:  
 1. 10 POCKETS HOLE PITCH CUMULATIVE TOLERANCE ±0.20mm.  
 2. COVER TAPE PEELING STRENGTH : 0.01 kgf MIN. 0.15 kgf MAX. AT 300mm/min.



3. PACKING CAPACITY :310 PCS/REEL, 3 REELS/BOX, TOTAL 930 PCS/BOX.

3	REEL	POLYSTYRENE
2	COVER TAPE	POLYESTER
1	CARRIER TAPE	POLYSTYRENE
ITEM	DESCRIPTION	MATERIAL

X. ± 1.5	X. °	UNITS mm	NAME(INTENDED USE) DDR4 SODIMM CONN.	FOXCONN FOXCONN INTERCONNECT TECHNOLOGY LIMITED.						
.X ± 1.0	.X °				MAT'L					
.XX ± 0.2	.XX °	FINISH	PART NO.(INTENDED USE) AS0A82*-H2SB-7H	TITLE: CUSTOMER DRAWING 260PIN SODDR4 5.2 STD.						
.XXX ±	.XXX °									
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED. AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			APPD: C.S Li	DWG NO.: 317-0000-2252						
			CHKD: Alex Wang							
			DR: Gary Xu 2013/10/11							
		QTY	<table border="1"> <tr> <td>SCALE</td> <td>SHEET</td> <td>REV.</td> </tr> <tr> <td>N/A</td> <td>5/5</td> <td>A</td> </tr> </table>		SCALE	SHEET	REV.	N/A	5/5	A
SCALE	SHEET	REV.								
N/A	5/5	A								

CONNECTOR P/N AS0A82\*-H2RB-7H